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N THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Anderson, et al.

Examiner: Baker

Appl. No:

09/803,319

Art Unit: 1

1639

Filed:

March 9, 2001

For:

USES AND METHODS OF MAKING MICROARRAYS OF POLYMER

BIOMATERIALS

Assistant Commissioner for Patents Washington, DC 20231

Sir:

STATEMENT FILED PURSUANT TO THE DUTY OF DISCLOSURE UNDER 37 CFR §§1.56, 1.97 AND 1.98

TECH CENTER 1600/2900

MAR 1 3 2003

Pursuant to the duty of disclosure under 37 C.F.R. §§1.56, 1.97 and 1.98, Applicants request consideration of this Supplemental Information Disclosure Statement.

PART I: Compliance with 37 C.F.R. §1.97

(Select A, B or C below)

- A. [X] This Supplemental Information Disclosure Statement has been filed (check 1, 2 and/or 3 below)
 - 1. [] within three months of the filing date of the above identified U.S. Patent application.
 - 2. [] within three months of the filing date of the entry of the National Stage, as set forth in 37 C.F.R. §1.491, in an International application.
 - 3. [X] before the mailing date of the first Office Action on the merits in the above-identified application.

No fee or certification is required.

B. [] This Supplemental Information Disclosure Statement has been filed more than three months after the filing date of the present application and after the mailing date of the first Office Action, but before the mailing date of either a final action under 37 C.F.R. §1.113 or a Notice of Allowance under 37 C.F.R. §1.311.

(check 1 or 2 below) 1. The fee of \$180 as set forth in 37 C.F.R. §1.17(p) is enclosed. The Applicants hereby certify, as specified in 37 C.F.R. §1.97(e), that 2. (check a or b below) [] each item of information contained in this Supplemental Information a. Disclosure Statement was cited in a communication from a foreign Patent Office in a counterpart for this application not more than three months prior to the filing of this Statement. 1 no item of information contained in this Supplemental Information b. Disclosure Statement was cited in a communication from a foreign Patent Office in a counterpart for this application or, to the knowledge of the undersigned after making reasonable inquiry, was known to any individual designated in 37 C.F.R. §1.56(c) more than three months prior to the filing of this Statement. items indicated by an asterisk were identified in a recent review of c. []related files. C. [] This Supplemental Information Disclosure Statement has been filed after the mailing date of either a Final action under 37 C.F.R. §1.113 or a Notice of Allowance under 37 C.F.R. §1.311 and before payment of an Issue Fee. (check a or b below) 1. The Applicants hereby certify, as specified in 37 C.F.R. §1.97(e), that: a. [] each item of information contained in this Supplemental Information Disclosure Statement was cited in a communication from a foreign Patent Office in a counterpart for this application not more than three months prior to the filing of this Statement.

b. [] no item of information contained in this Supplemental Information

Disclosure Statement was cited in a communication from a foreign Patent

Office in a counterpart for this application or, to the knowledge of the

undersigned after making reasonable inquiry, was known to any individual

designated in 37 C.F.R. §1.56(c) more than three months prior to the filing

of this Statement.

PART II - Information Cited

- [X] A. Applicants hereby make of record in the above-identified application the reference(s) listed on the attached form PTO-1449 (modified). The order of presentation of the references should not be construed as an indication of the importance of the references.
- [] B. The Applicants hereby make the following additional information of record in the above-identified application:
- [] PART III: Explanation of Non-English Language References and Remarks Concerning
 Other Information Cited

The following is a concise explanation of the relevance of each non-English language reference listed on the attached form PTO-1449 (modified):

The following are remarks concerning the other information cited:

PART IV: Remarks

A copy of each of the above-identified U.S. and foreign patent(s) and publication(s) is enclosed unless otherwise indicated on the attached form PTO-1449 (modified). It is respectfully requested that:

1. The Examiner consider completely the cited information, along with any other information, in reaching a determination concerning the patentability of the present claims;

The enclosed form PTO-1449 be signed by the Examiner to evidence that the 2. cited patent(s) and publication(s) has (have) been fully considered by the Patent and Trademark

Office during the examination of this application; and

The citations for the patent(s) and publication(s) be printed on any patent which 3.

issues from this application.

By submitting this Supplemental Information Disclosure Statement, Applicants make no

representation that a search has been performed, of the extent of any search performed, or that

more material information may not exist.

By submitting this Supplemental Information Disclosure Statement, Applicants make no

representation that the information cited in the Statement is, or is considered to be, material to

patentability as defined in 37 C.F.R. §1.56(b).

By submitting this Supplemental Information Disclosure Statement, Applicants make no

representation that the information cited in the Statement is, or is considered to be, in fact, prior

art as defined by 35 U.S.C. §102.

Notwithstanding any statements by Applicants, the Examiner is urged to form his or her

own conclusions regarding the relevance of the cited reference(s).

An early and favorable action is hereby requested.

Respectfully submitted,

Charles Lyon, Ph.D.

Agent for Applicant

Limited Recognition Under 37 CFR 10.9(b)

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Dated: Mard 5, 2003

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I hereby certify that this correspondence is deposited with the United States Postal Service as first Assistant addressed to: mail in an envelope 20231 Washington, D.C. Patents,